Characteristics STTH802

Characteristics 1

Absolute ratings (limiting values at $T_i = 25^{\circ}$ C, unless otherwise specified) Table 1.

Symbol	Parameter			Value	Unit		
V _{RRM}	Repetitive peak	reverse voltage			200	V	
I _{F(RMS)}	RMS forward cu	ırrent			16	А	
	Average	TO-220A, DPAK, D ² PAK		T _c = 145° C	_		
I _{F(AV)}	forward current, $\delta = 0.5$	TO-220FPAC	T _c = 125° C		8	Α	
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms Sinusoidal		100	А		
T _{stg}	Storage temper	emperature range			-65 to + 175	° C	
Tj	Maximum operating junction temperature			175	° C		

Table 2. **Thermal parameters**

Symbol	Pa	Parameter		
D	Junction to case	TO-220AC, DPAK, D ² PAK	3.2	° C/W
R _{th(j-c)}	Junction to case	TO-220FPAC	5.5	C/VV

Table 3. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Тур	Max.	Unit
I _B ⁽¹⁾	T _j = 25° C				6		
I 'R`	I _R ⁽¹⁾ Reverse leakage current	T _j = 125° C	$V_R = V_{RRM}$		6	60	μΑ
V _E ⁽²⁾	(2) Equipped voltage drap $T_j = 25^{\circ} \text{ C}$		0.95	1.05	V		
V _F ⁽²⁾ Forward voltage drop	T _j = 150° C	I _F = 8 A		0.8	0.90	V	

- 1. Pulse test: $t_p = 5$ ms, $\delta < 2$ %
- 2. Pulse test: t_p = 380 μ s, δ < 2 %

To evaluate the conduction losses use the following equation: P = 0.73 x $I_{F(AV)}$ + 0.021 $I_{F}^{2}_{(RMS)}$

$$P = 0.73 \times I_{F(AV)} + 0.021 I_{F^2(BMS)}$$

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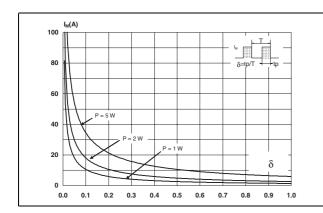
STTH802 Characteristics

Table 4. Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Тур	Max.	Unit
+	Reverse recovery time	$I_F = 1 \text{ A, } dI_F/dt = -50 \text{ A/}\mu\text{s,}$ $V_R = 30 \text{ V, } T_j = 25 \text{ °C}$		25	30	ns
t _{rr}	Heverse recovery time	$I_F = 1 \text{ A, } dI_F/dt = -100 \text{ A/}\mu\text{s,}$ $V_R = 30 \text{ V, } T_j = 25 \text{ °C}$		17	22	
I _{RM}	Reverse recovery current	$I_F = 8 \text{ A}, dI_F/dt = -200 \text{ A/}\mu\text{s},$ $V_R = 160 \text{ V}, T_j = 125 ^{\circ}\text{C}$		5.5	7	Α
t _{fr}	Forward recovery time	$I_F = 8 \text{ A}, dI_F/dt = 50 \text{ A}/\mu\text{s}$ $V_{FR} = 1.1 \text{ x } V_{Fmax}, T_j = 25 \text{ °C}$		150		ns
V _{FP}	Forward recovery voltage	$I_F = 8 \text{ A, d}I_F/\text{d}t = 50 \text{ A/}\mu\text{s,}$ $T_j = 25 ^{\circ}\text{C}$		1.5		V

Figure 1. Peak current versus duty cycle

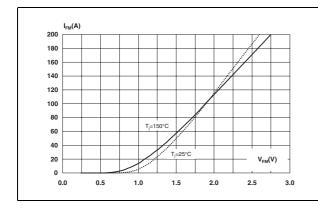
Figure 2. Forward voltage drop versus forward current (typical values)

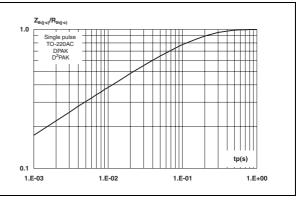


180
160
140
120
100
80
60
40
20
0.0
0.5
1.0
1.5
2.0
2.5
3.0

Figure 3. Forward voltage drop versus forward current (maximum values)

Figure 4. Relative variation of thermal impedance, junction to case, versus pulse duration (TO-220AC, DPAK, D²PAK)

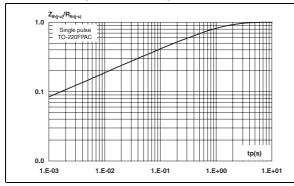




Characteristics STTH802

Figure 5. Relative variation of thermal impedance, junction to case, versus pulse duration (TO-220FPAC)

Figure 6. Junction capacitanceversus reverse applied voltage (typical values)



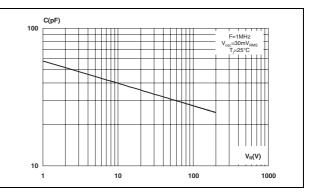
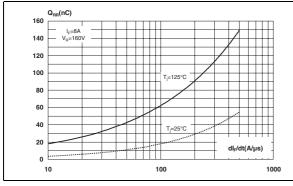


Figure 7. Reverse recovery charges versus dl_F/dt (typical values)

Figure 8. Reverse recovery time versus dl_F/dt (typical values)



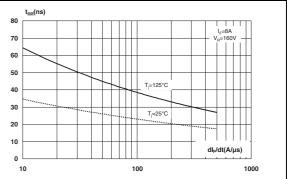
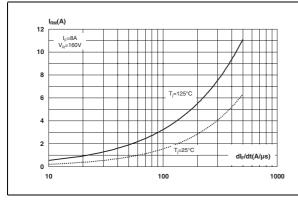


Figure 9. Peak reverse recovery current versus dl_F/dt (typical values)

Figure 10. Dynamic parameters versus junction temperature



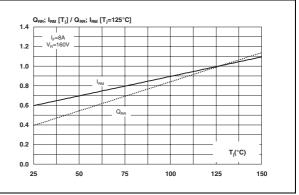
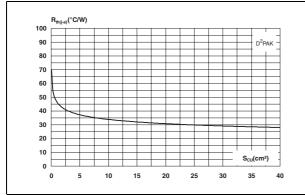
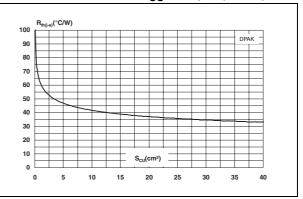


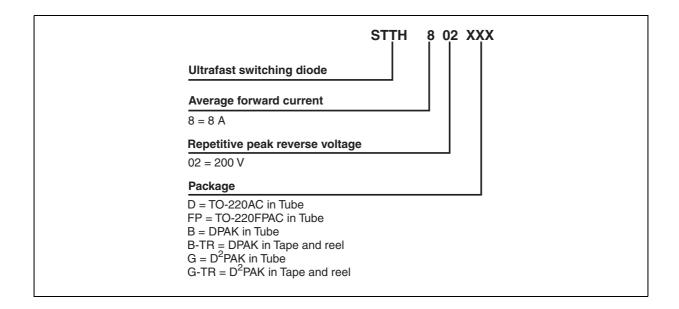
Figure 11. Thermal resistance, junction to ambient, versus copper surface under tab - Epoxy printed circuit board FR4, e_{CU} = 35 μ m (D²PAK)

Figure 12. Thermal resistance, junction to ambient, versus copper surface under tab - Epoxy printed circuit board FR4, e_{CU} = 35 μm (DPAK)





2 Ordering information scheme



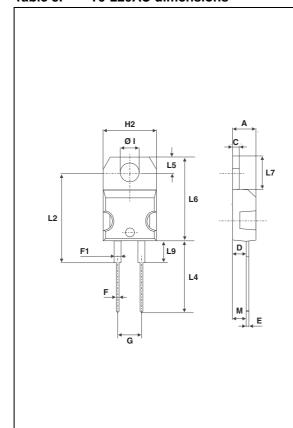
Package information STTH802

3 Package information

Epoxy meets UL94, V0

Cooling method: by conduction (C)
Recommended torque value: 0.8 Nm
Maximum torque value: 1.0 Nm

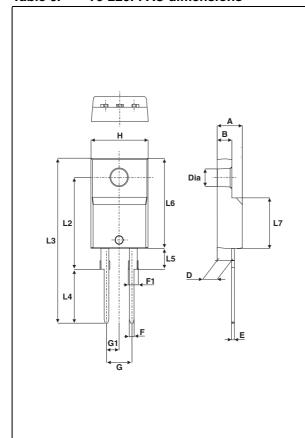
Table 5. T0-220AC dimensions



		DIMEN	ISIONS	
REF.	Millimeters		Inc	hes
İ	Min.	Max.	Min.	Max.
Α	4.40	4.60	0.173	0.181
С	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
Е	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
H2	10.00	10.40	0.393	0.409
L2	16.40	O typ.	0.645 typ.	
L4	13.00	14.00	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
М	2.6 typ.		0.102	2 typ.
Diam. I	3.75	3.85	0.147	0.151

STTH802 Package information

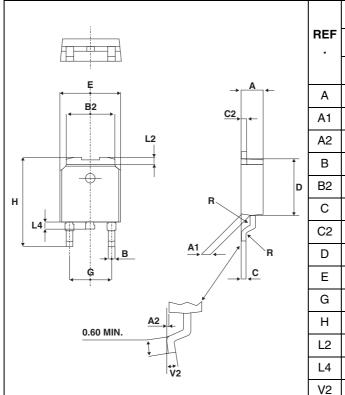
Table 6. T0-220FPAC dimensions



	DIMENSIONS					
REF	Millim	neters	Inc	hes		
	Min.	Max.	Min.	Max.		
Α	4.4	4.6	0.173	0.181		
В	2.5	2.7	0.098	0.106		
D	2.5	2.75	0.098	0.108		
Е	0.45	0.70	0.018	0.027		
F	0.75	1	0.030	0.039		
F1	1.15	1.70	0.045	0.067		
G	4.95	5.20	0.195	0.205		
G1	2.4	2.7	0.094	0.106		
Н	10	10.4	0.393	0.409		
L2	16	Тур.	0.63	Тур.		
L3	28.6	30.6	1.126	1.205		
L4	9.8	10.6	0.386	0.417		
L5	2.9	3.6	0.114	0.142		
L6	15.9	16.4	0.626	0.646		
L7	9.00	9.30	0.354	0.366		
Dia.	3.00	3.20	0.118	0.126		

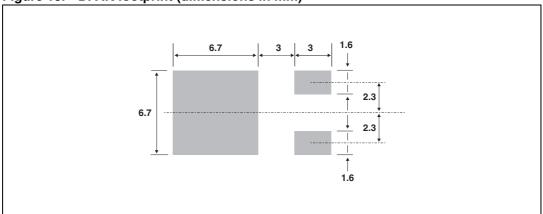
Package information STTH802

Table 7. DPAK dimensions



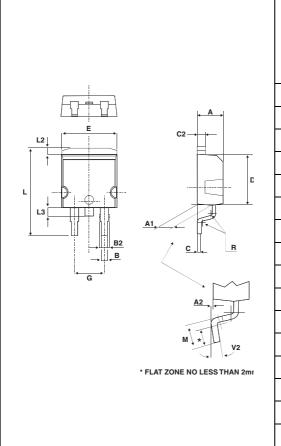
	DIMENSIONS				
REF	Millimeters		Inc	hes	
	Min.	Max	Min.	Max.	
Α	2.20	2.40	0.086	0.094	
A1	0.90	1.10	0.035	0.043	
A2	0.03	0.23	0.001	0.009	
В	0.64	0.90	0.025	0.035	
B2	5.20	5.40	0.204	0.212	
С	0.45	0.60	0.017	0.023	
C2	0.48	0.60	0.018	0.023	
D	6.00	6.20	0.236	0.244	
Е	6.40	6.60	0.251	0.259	
G	4.40	4.60	0.173	0.181	
Н	9.35	10.10	0.368	0.397	
L2	0.80 typ.		0.03	1 typ.	
L4	0.60	1.00	0.023	0.039	
V2	0°	8°	0°	8°	

Figure 13. DPAK footprint (dimensions in mm)



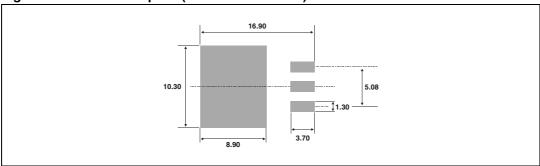
STTH802 Package information

Table 8. D²PAK dimensions



		Dimer	nsions	
Ref.	Millim	neters	Inc	hes
	Min.	Max.	Min.	Max.
Α	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
A2	0.03	0.23	0.001	0.009
В	0.70	0.93	0.027	0.037
B2	1.14	1.70	0.045	0.067
С	0.45	0.60	0.017	0.024
C2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
Е	10.00	10.40	0.393	0.409
G	4.88	5.28	0.192	0.208
L	15.00	15.85	0.590	0.624
L2	1.27	1.40	0.050	0.055
L3	1.40	1.75	0.055	0.069
М	2.40	3.20	0.094	0.126
R	0.40 typ.		0.016	6 typ.
V2	0°	8°	0°	8°

Figure 14. D²PAK footprint (dimensions in mm)



In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

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Ordering information STTH802

4 Ordering information

Part Number	Marking	Package	Weight	Base qty	Delivery mode
STTH802D	STTH802	TO-220AC	1.86 g	50	Tube
STTH802FP	STTH802	TO-220FPAC	2.2 g	50	Tube
STTH802B	STTH802	DPAK	0.3 g	75	Tube
STTH802B-TR	STTH802	DPAK	0.3 g	2500	Tape and reel
STTH802G	STTH802	D ² PAK	1.48 g	50	Tube
STTH802G-TR	STTH802	D ² PAK	1.48 g	1000	Tape and reel

5 Revision history

Date	Revision	Description of Changes
03-May-2006	1	First issue
22-Sep-2006	2	Added D ² PAK package

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